



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Do Not

Application No.: 09/464,322

Filing Date: December 15, 1999

Applicant: Heung-Kyu KWON et al.

Group Art Unit: 2815

Examiner: Chris C. CHU

Title: SEMICONDUCTOR CHIP PACKAGE AND METHOD OF
FABRICATING THE SAME

Attorney Docket: 25611-000085/US

Enter

C.C.

7/18/07

Customer Service Window
Randolph Building
401 Dulany Street
Alexandria, VA 22314
Mail Stop: Amendment

July 9, 2007

AMENDMENT

Sir:

In response to the Office Action mailed May 2, 2007, the following remarks are respectfully submitted in connection with the above-identified application.

Listing of the Claims begin on page 3 of this Amendment.

Remarks begin on page 7 of this Amendment.

| | Claims remaining after Amendment | | Highest number previously paid for | | Present extra |
|-------------|-------------------------------------|---|---------------------------------------|---|---------------|
| Total | 18 | - | 20 | = | 0 |
| Independent | 3 | - | 3 | = | 0 |